

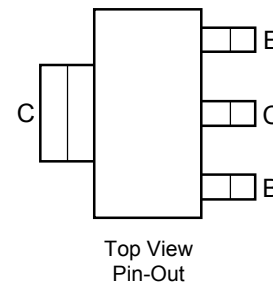
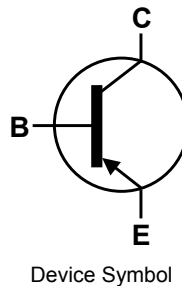
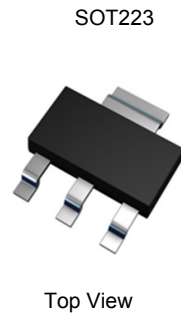
**500V PNP HIGH VOLTAGE TRANSISTOR IN SOT223**

**Features**

- $BV_{CEO} > -500V$
- $I_C = -150mA$  High Continuous Current
- $I_{CM} = -500mA$  Peak Pulse Current
- **Lead-Free Finish; RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

**Mechanical Data**

- Case: SOT223
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 Ⓔ
- Weight: 0.112 grams (approximate)

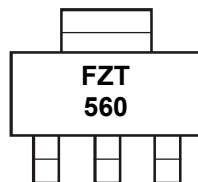


**Ordering Information** (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
FZT560TA	AEC-Q101	FZT560	7	12	1,000
FZT560QTA	Automotive	FZT560	7	12	1,000
FZT560TC	AEC-Q101	FZT560	13	12	4,000
FZT560QTC	Automotive	FZT560	13	12	4,000

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to [http://www.diodes.com/quality/product\\_compliance\\_definitions/](http://www.diodes.com/quality/product_compliance_definitions/).
  5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>

**Marking Information**



FZT560 = Product Type Marking Code

### Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-500	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-500	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	I <sub>C</sub>	-150	mA
Peak Pulse Current	I <sub>CM</sub>	-500	mA

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

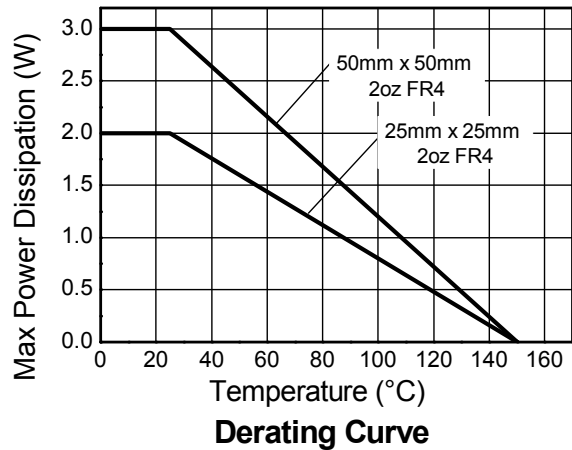
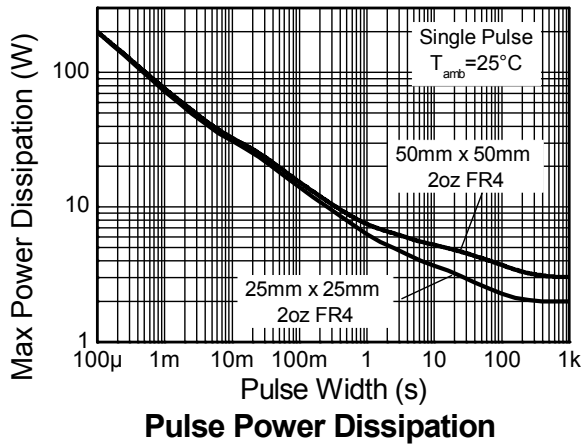
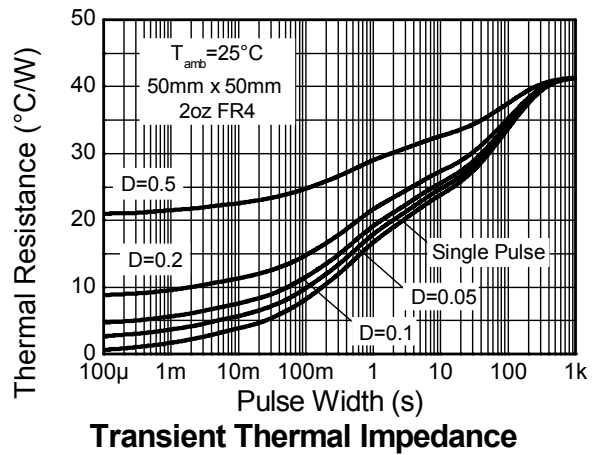
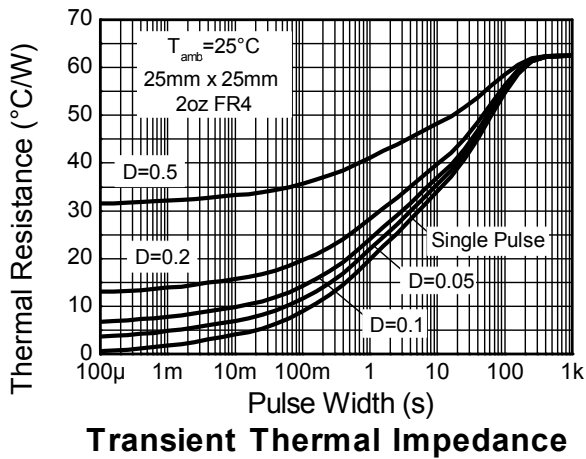
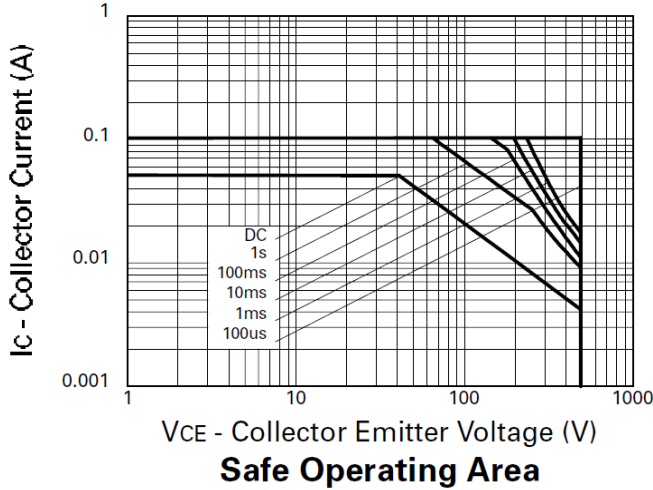
Characteristic	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	(Note 6) 2	W
		(Note 7) 3	W
Thermal Resistance, Junction to Ambient	R <sub>θJA</sub>	(Note 6) 62.5	°C/W
		(Note 7) 41.7	°C/W
Thermal Resistance, Junction to Leads	R <sub>θJL</sub>	14.8	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

### ESD Ratings (Note 9)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted with the collector lead on 25mm x 25mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady-state.
  7. Same as note (6), except the device is mounted on 50mm x 50mm 2oz copper.
  8. Thermal resistance from junction to solder-point (at the end of the collector lead).
  9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

**Thermal Characteristics and Derating Information**

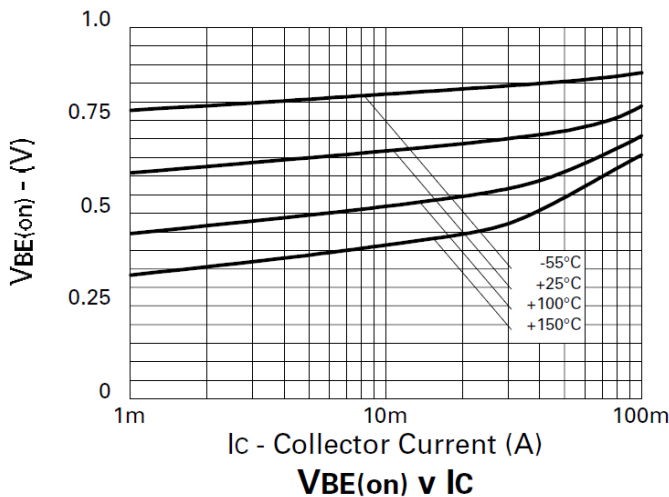
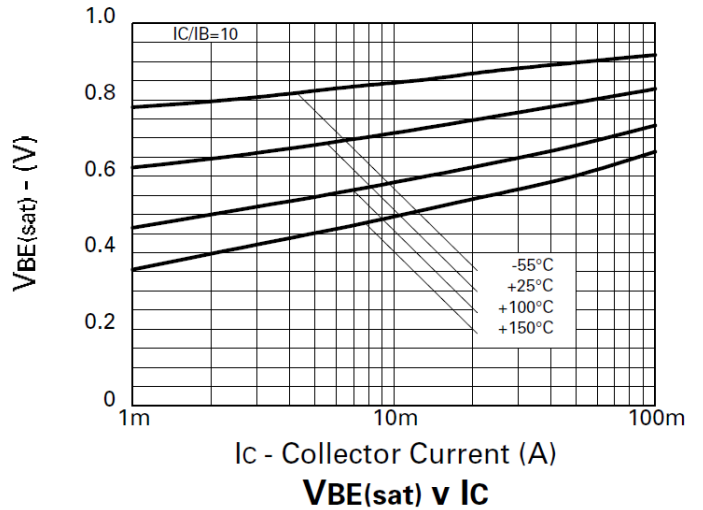
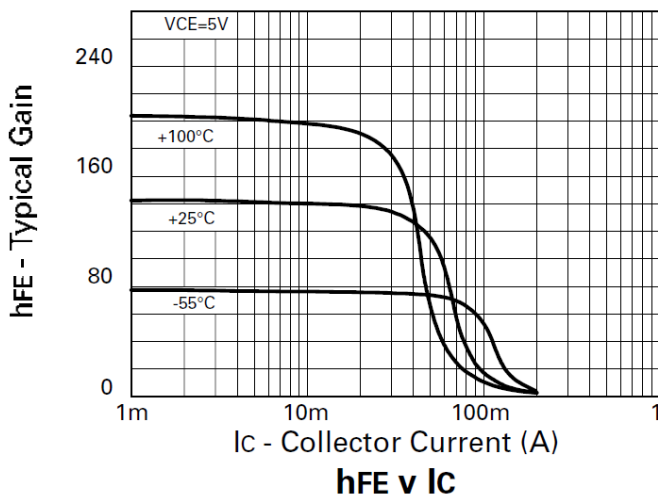
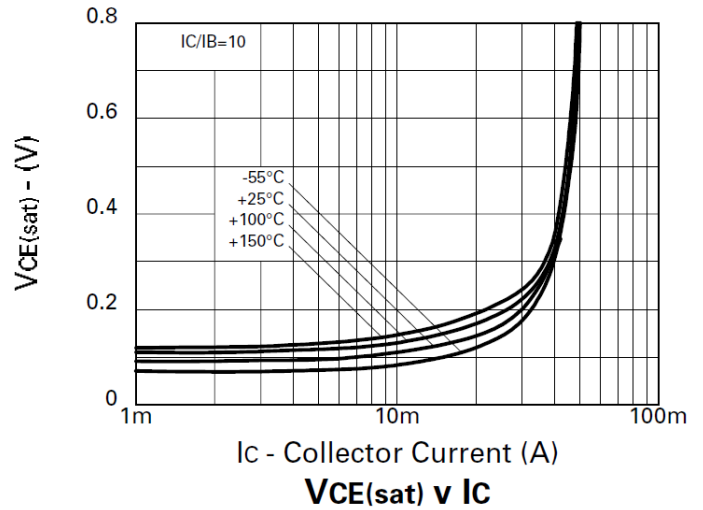
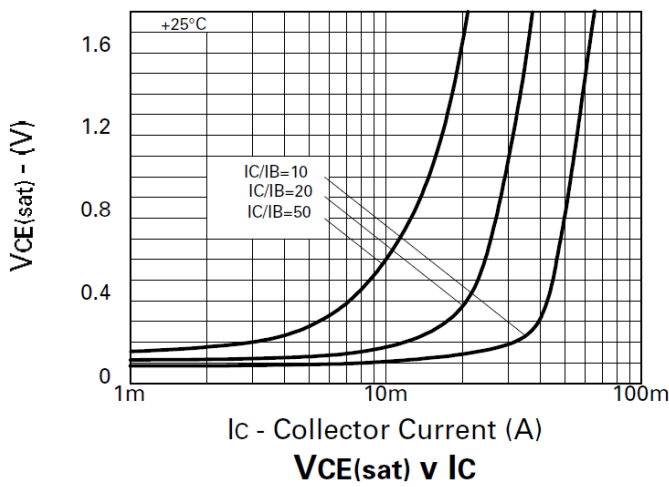


**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	-500	-	-	V	$I_C = -100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 10)	$BV_{CEO}$	-500	-	-	V	$I_C = -1\text{mA}$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	-7	-	-	V	$I_E = -100\mu\text{A}$
Collector Cut-off Current	$I_{CBO}$	-	-	-100	nA	$V_{CB} = -500\text{V}$
Collector Cut-off Current	$I_{CES}$	-	-	-100	nA	$V_{CE} = -500\text{V}$
Emitter Cut-off Current	$I_{EBO}$	-	-	-100	nA	$V_{EB} = -5.6\text{V}$
Collector-Emitter Saturation Voltage (Note 10)	$V_{CE(sat)}$	-	-	-200	mV	$I_C = -20\text{mA}, I_B = -2\text{mA}$
		-	-	-500		$I_C = -50\text{mA}, I_B = -10\text{mA}$
Base-Emitter Saturation Voltage (Note 10)	$V_{BE(sat)}$	-	-	-900	mV	$I_C = -50\text{mA}, I_B = -10\text{mA}$
Base-Emitter Turn-On Voltage (Note 10)	$V_{BE(on)}$	-	-	-900	mV	$I_C = -50\text{mA}, V_{CE} = -10\text{V}$
DC Current Gain (Note 10)	$h_{FE}$	100	-	300	-	$I_C = -1\text{mA}, V_{CE} = -10\text{V}$
		80	-	300		$I_C = -50\text{mA}, V_{CE} = -10\text{V}$
		-	15	-		$I_C = -100\text{mA}, V_{CE} = -10\text{V}$
Current Gain-Bandwidth Product	$f_T$	60	-	-	MHz	$V_{CE} = -20\text{V}, I_C = -10\text{mA}$ $f = 50\text{MHz}$
Turn-On Time	$t_{on}$	-	110	-	ns	$V_{CC} = -100\text{V}, I_C = -50\text{mA}$
Turn-Off Time	$t_{off}$	-	1.5	-	$\mu\text{s}$	$I_{B1} = -5\text{mA}, I_{B2} = 10\text{mA}$
Output Capacitance	$C_{obo}$	-	-	8	pF	$V_{CB} = -20\text{V}, f = 1\text{MHz}$

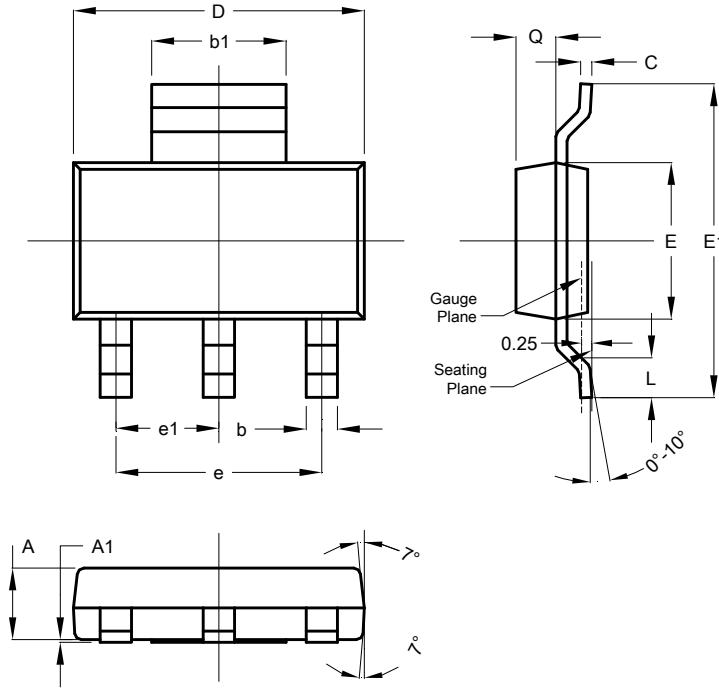
Notes: 10. Measured under pulsed conditions. Pulse width  $\leq 300 \mu\text{s}$ . Duty cycle  $\leq 2\%$

**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



**Package Outline Dimensions**

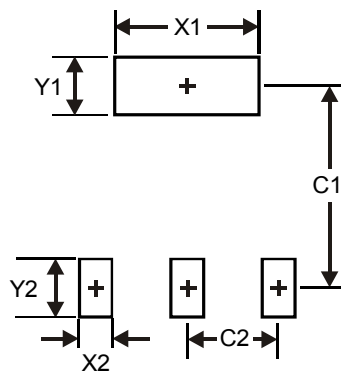
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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